

PATENT NUMBER

U.S. UTILITY Patent Application

J.P.E.

PATENT DATE

SCANNED Q.A. A-G

APPLICATION NO. 09/854759	CONT/PRIOR	CLASS 156	SUBCLASS 247	ART UNIT 1734 1733	EXAMINER Haran
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APPLICANTS

Michael Ball
Jose Sanchez

TITLE

Using backgrind wafer tape to enable wafer mounting of bumped wafers

PTO-2040
12/99

ISSUING CLASSIFICATION

ORIGINAL			CROSS REFERENCE(S)								
CLASS		SUBCLASS	CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)							
INTERNATIONAL CLASSIFICATION											

TERMINAL DISCLAIMER

DRAWINGS

CLAIMS ALLOWED

Sheets Drwg.

Figs. Drwg

Print Fig.

Total Claims

Print Claim for O.G.

☐ The term of this patent subsequent to _____ (date) has been disclaimed.

____ (date)

☐ The term of this patent shall not extend beyond the expiration date of U.S. Patent No. _____

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(Date)

NOTICE OF ALLOWANCE MAILED

ISSUE FEE

Amount Due

Date Paid:

ISSUE BATCH NUMBER

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(Rev. 6/99)

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(FACE)